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(54) MANUFACTURE OF COPPER POLYIMIDE BOARD

(57)Abstract:

PURPOSE: To provide a copper polyimide board which enables a conventional process for eliminating a base metal layer to be adopted with negligible reduction in adhesion strength when left for a long time under a high- temperature environment without losing adhesion strength between copper and a polyimide resin film.

CONSTITUTION: A surface of a polyimide resin film is turned into hydrophilic, a catalyst is given, electroless plating is performed, and then electroless copper plating or electrical copper plating is performed, thus enabling a copper polyimide board to be manufactured. An aqueous solution which is at 10-50°C containing 1-15mol/l hydrazine hydrate and 0.5-5mol/l alkali metal hydride is used for hydrophilic treatment of the polyimide resin film and either one of nickel, cobalt, or their alloy is subjected to electroless plating after giving the catalyst, thus forming a plating layer with a thickness of 0.01-0.1μm and an impurity quality of 10% or less.

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